

IEEE-EPS Malaysia Chapter AGM – 12th Feb 2022

This year IEEE EPS Malaysia Chapter held their AGM 100% Online. Please join me in congratulating the incoming IEEE Electronic Packaging Society (EPS) Malaysia Chapter committee that is led by Dr Yik Yee TAN.

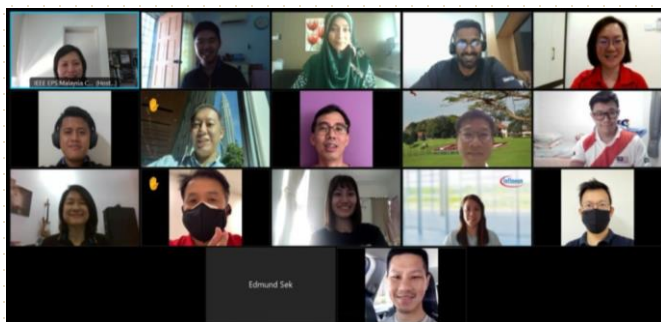


Fig 1: IEEE EPS Malaysia Chapter Online AGM Group Photo.

IEEE EPS Malaysia 2022 Committee

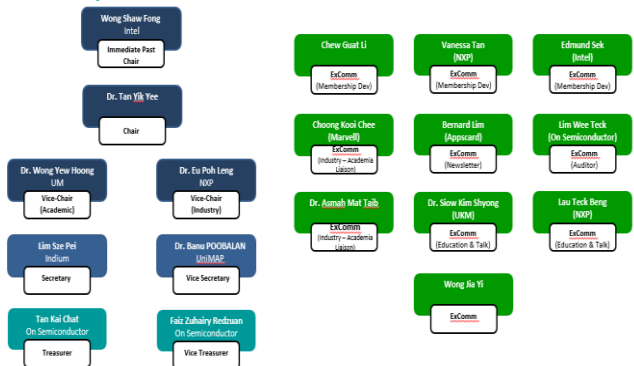


Fig 2: IEEE EPS Malaysia Committee 2022

IEEE EPS Malaysia Chapter won the IEEE Malaysia Section – 2021 Outstanding Small Chapter Award

During the 2022 IEEE Malaysia Section AGM held at Kuala Lumpur Convention Centre on 12th Feb 2022, IEEE EPS Malaysia Chapter, chaired by Dr Yik Yee Tan won the 2021 Outstanding Small Chapter Award. The purpose of the award is to recognize the outstanding performance of the small chapter among all the small chapters in Malaysia Section.

The award was presented by the IEEE Malaysia Section Chair, Dr Md Pauzi. IEEE EPS Malaysia Chapter Vice chair, Dr Eu Poh Leng received the award on behalf of the chapter (Figure 3).



Congratulations to IEEE EPS Malaysia Chapter Volunteers!!!

IEEE EPS Webinar Series 2022

EPS Webinar Series 2022

Topic 1: Flip chip die attach fluxes from industry perspective



Speaker: Mr. Azham Mohd Sukerni
Senior Principal Engineer, Package Innovation Dept., NXP Semiconductor Malaysia

Topic 2: Reliability issues related to No-clean Flux



Speaker 1: Prof. A. S. M. A. Haseeb
Professor of Mechanical Engineering Dept., University of Malaya (UM)

Speaker 2: Mr. Saif Wakeel
Ph.D. researcher at Tyndall National Institute, University College Cork, Ireland

Date : 22-Mar-2022 (Tue)
Time : 10.00am – 11.30am
Platform : IEEE CISCO WebEx

E-certificates will be provided to participants

Organized by:

On 22nd Mar 2022, IEEE EPS Malaysia Chapter, held a webinar talk by UM and NXP. The webinar was moderated by IEEE EPS Malaysia Chapter Vice Chair, Dr Eu Poh Leng. The talk was collaboration between IEEE EPS Malaysia Chapter, NXP and UM. This is indeed a great collaboration between the industry and academia. There were two topics delivered: Topic 1: Flip Chip Die Attach Fluxes from Industry Perspective and Topic 2: Reliability issues related to No-Clean Flux.



Best Engineering Student Award (BESA) 2022 for Undergraduate Final Year Project

As previous years, IEEE EPS Malaysia Chapter has a regular flagship “Best Engineering Student Award (BESA) for Undergraduates. This year, IEEE EPS Malaysia Chapter decided to introduce additional two (2) special awards under BESA 2022/2023, namely Prof. K.N. Seetharamu BESA (Thermal Engineering) and Azhar Aripin BESA (Simulation and Modelling).

Both Prof. Seetharamu and Azhar were the among the founding members since the earlier days of IEEE EPS Malaysia Chapter and they have contributed significantly to the chapter.



Prof. Dr. Kankanhalli Seetharamu

Founder of IEEE EPS Malaysia Chapter

Kankanhalli N. Seetharamu (SM'03) received the B.E. degree from Mysore University, Mysore, India, in 1960; the M.E. degree from the Indian Institute of Science, Bangalore, in 1962, and the Ph.D. degree from the Indian Institute of Technology (IIT), Madras, in 1973. He was a Professor of mechanical engineering at IIT, Madras, for almost three decades before joining USM, Malaysia in 1998 and left USM in 2004. Dr. Seetharamu was the President of IEEE CPMT Chapter of Malaysia and the Secretary/Treasurer of IMAPS Malaysia Chapter. He was responsible for starting both the IEEE-CPMT and IMAPS chapters in Malaysia.



Azhar Aripin

EMT 2008 General Chair
EMT 2010 to 2016 Treasurer
IEEE EPS Malaysia Chair and Treasurer

Azhar graduated from the University of Iowa with a Bachelor of Mechanical Engineering in 1992. He started his career as an R&D engineer with Motorola KL Malaysia. Later, he joined ON Semiconductor Seremban (spin out company from Motorola). He has published numerous publications and filed several patents during his entire career in ON Semiconductor.

Prof. K.N. Seetharamu BESA 2022 Award:

- Must demonstrate exceptional merit, i.e. technical contribution, achievement, or innovation in the niche area of Thermal Engineering for electronic packaging.
- The submitted entry must demonstrate as outstanding work, which have won prize(s) in contest or competition or technical meeting or suite of meetings or have published in a WOS/ISI indexed journal or other related form.

Azhar Aripin BESA 2022 Award:

- Must demonstrate exceptional merit, i.e. technical contribution, achievement, or innovation in the niche area of Modelling & Simulation for electronic packaging.
- The submitted entry must demonstrate as outstanding work, which have won prize(s) in contest or competition or technical meeting or suite of meetings or have published in a WOS/ISI indexed journal or other related form.

IEEE EPS Malaysia Chapter humanitarian effort - Education Support to Azhar Aripin

IEEE EPS Malaysia Chapter Chair, Dr Tan proposed to use the interest from the chapter FD to support Azhar's kids' education, RM3,000 every year for 3 years.

On the 1st April, IEEE EPS vice chair, Dr Eu Poh Leng visited Azhar's wife to present the education fund as well as sharing a little about the purpose of the fund.

